EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	1	"20050079664"	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/08/28 15:20
S2	8	"6335501"	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/10/11 17:58
S3	22	"6103597"	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/10/11 18:51
S4	6	(("6355501") or ("6335501") or ("6103597") or ("6221738") or ("6100166") or ("6184111")).PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2005/10/11 18:54
S5	294	faris-sadeg-m.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/10/13 17:47
S6	12	S5 and substrate and strong and weak and bond$4 and remov$4 and vertical$4	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/10/13 18:16
S7	1	"10719663"	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/10/13 18:16
S8	6	("4903118" | "6159323" | "6316333" | "6342433" | "6355501" | "6777312").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/13 18:16
S9	11	("4727047" | "5371037" | "5650353" | "5811348" | "5854123" | "5856229" | "5897743" | "6020252" | "6091112" | "6107213" | "6140210").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/13 18:23
S10	4	("4727047" | "5250460" | "5362638" | "5459081").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/13 18:36
S11	45	("5811348").URPN.	USPAT	OR	ON	2005/10/13 18:38
S12	45	("5811348").URPN.	USPAT	OR	ON	2005/10/13 18:45
S13	77	"6084781"	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/03/30 13:01
S14	70	S13 and (remov$3 or detact$3 or depond$3 or de-bond$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/03/30 13:09
S15	0	S14 and (buried near2 $2oxide)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/03/30 13:03

EAST Search History

S16	32	S14 and ($2oxide)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/03/30 13:04
S17	32	S16 and (substrate or wafer or base or board) and (contact$3 or electrode or pad or bump or terminal)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/03/30 13:05
S18	31	S17 and (@ad<"20021120" or @rlad<"20021120")	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/03/30 13:20
S19	22255	(substrate or wafer or board or base) and (remov$3 or detact$3 or depond$3 or de-bond$3) and ((buried or dop$3 or implant$4) near2 $2oxide)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/03/30 14:33
S20	1926	438/455-458.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/03/30 13:18
S21	1099	257/e21.567-e21.568.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/03/30 13:20
S22	19162	(S19 S20 S21) and (@ad<"20021120" or @rlad<"20021120") and (remov$3 or detact$3 or depond$3 or de-bond$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/03/30 14:21
S23	38	(S19 S20 S21) and (@ad<"20021120" or @rlad<"20021120") and (detact$3 or depond$3 or de-bond$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/03/30 14:52
S24	601	(S22 not S23) and (strong$3 near2 (attach$4 or bond$3 or stick$3 or past$3))	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/03/30 14:36
S25	88	S24 and (weak$3 near2 (attach$4 or bond$3 or stick$3 or past$3))	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/03/30 14:35
S26	57	S25 and (implant$5)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/03/30 13:31
S27	37	S25 and (implant$4 with $2oxide)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/03/30 14:53
S28	1	"6956268"	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/03/30 13:37

EAST Search History

S29	1171	438/455.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/03/30 14:24
S30	88	H01L21/30.IPC.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/03/30 14:24
S31	730	((substrate or wafer or board or base) and (remov$3 or detact$3 or depond$3 or de-bond$3 or split$3) and ((buried or dop$3 or implant$4) near2 $2oxide)).clm.	US-PGPUB	OR	ON	2006/03/30 14:50
S32	724	S31 not (S18 S23 S27 S28 S30)	US-PGPUB	OR	ON	2006/03/30 14:51
S33	7	S24 and (weak$3 near2 (attach$4 or bond$3 or stick$3 or past$3)).clm.	US-PGPUB	OR	ON	2006/03/30 14:36
S34	1	S32 and (strong$3 near2 (attach$4 or bond$3 or stick$3 or past$3)).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/03/30 14:36
S35	1634	((substrate or wafer or board or base) with (handl$3 or donor$3)) and (remov$3 or detact$3 or depond$3 or de-bond$3 or split$3) and ((buried or dop$3 or implant$4) near2 $2oxide)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/03/30 14:51
S36	97	(S35 not (S18 S23 S27 S28 S30 S34 S33)) and (@ad<"20021120" or @rlad<"20021120") and (detact$3 or depond$3 or de-bond$3 or split$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/03/30 14:52
S37	49	S36 and (implant$4 with $2oxide)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/03/30 14:53
S39	129	("4309225"|"4370176"|"4371421"|"4471003"|"4479846"|"4500563"|"4585945"|"4816420"|"4837182"|"4846931"|"4883561"|"5273616"|"5362682"|"5374564"|"5453153"|"5559043"|"5588994"|"5676752"|"5710057"|"5714395"|"5793115"|"5845123"|"5877070"|"5882987"|"5897939"|"5909627"|"5920764"|"5933750"|"5976953"|"5985688"|"5993677"|"5994207"|"0006020"|"6027988"|"6033974"|"6054363"|"6054370"|"6059877"|"6071795"|"6103597"|"6137110"|"6146979"|"6155909"|"6159323"|"6159824"|"6159825"|"6162705"|"6184060"|"6184111"|"6187110"|"6190937"|"6190998"|"6191007"|"6204151"|"6214733"|"6221738"|"6221740"|"6221774"|"6225190"|"6225192"|"6232136"|"6309945"|"6387736").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/28 16:37
S40	107	S39 and (bond$4 rebond$4 depond$4 detach$4 remov$4 separat$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/28 20:15
S41	98	S40 and (depond$4 detach$4 remov$4 separat$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/28 17:36
S42	1	S41 and strong and week	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/28 17:28

EAST Search History

S43	46	S41 and ((buri$3 or embed$4) near2 ($2oxide insulat$3 dielectric) or "SOI")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/28 17:36
S44	54	"6355501"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/28 17:36
S45	28	S44 and (depond$4 detach$4 remov$4 separat$4) and ((buri$3 or embed$4) near2 ($2oxide insulat$3 dielectric) or "SOI")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/28 17:37
S46	7	S45 and (@ad<"20010912" @rlad<"20010912")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/28 18:24
S47	46	S43 and (@ad<"20010912" @rlad<"20010912")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/28 17:41
S48	1	"10719663"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/28 19:51
S49	4205	257/415,417-420,619,620,e21.567,e21.568e21.569,e21.571. ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/28 19:52
S50	4758	438/48-50,415,417,418,455-459.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/28 19:53
S51	107	H01L29/82.ipc.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/28 19:54
S52	227	H01L21/30.ipc.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/28 19:56
S53	1289	438/455.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/28 20:12

EAST Search History

S54	910	438/458.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/28 20:15
S55	6249	(S49 S50) and ((bond$4 rebond$4 depond$4 detach$4 remov$4 separat$4) same (substrate wafer carrier board base support$3 handl$4 donor$3))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/28 20:17
S56	4208	257/415,417-420,619,620,e21.567,e21.568e21.569,e21.571. ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/29 11:56
S57	4763	438/48-50,415,417,418,455-459.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/29 11:56
S58	6257	(S56 S57) and ((bond$4 rebond$4 depond$4 detach$4 remov$4 separat$4) same (substrate wafer carrier board base support$3 handl$4 donor$3))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/29 11:58
S59	5725	S58 and ((rebond$4 depond$4 detach$4 remov$4 separat$4) same (substrate wafer carrier board base support$3 handl$4 donor$3))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/29 13:38
S60	5011	S58 and ((rebond$4 depond$4 detach$4 remov$4 separat$4) with (substrate wafer carrier board base support$3 handl$4 donor$3))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/29 12:15
S61	3736	S60 and (@ad<"20021120" @rlad<"20021120")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/29 11:59
S62	1616	S61 and ((strong or streng$5 or great$3 high$3) with (bond$4 glue$4 stick$4 past$4 attach$4 adhes$4 coupl$3))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/29 17:09
S63	1029	S62 and ((week$4 weak$4 low$3 less$3) with (bond$4 glue$4 stick$4 past$4 attach$4 adhes$4 coupl$3))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/29 17:03
S64	1123	S61 and (("SOI" or ((buried embed$3) with ($2oxide dielectric insulat$3))) with (substrate wafer carrier board base support$3 handl$4 donor$3))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/29 17:10

S65	445	S63 and S64	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/29 12:09
S66	359	S65 and (@ad<"20010912" @rlad<"20010912")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/29 12:11
S67	309	S66 and (("SOI" or ((buried embed$3) near3 ($2oxide dielectric insulat$3))) near3 (substrate wafer carrier board base support$3 handl$4 donor$3))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/29 12:14
S68	291	S67 and ((rebond$4 depond$4 detach$4 remov$4 separat$4) near5 (substrate wafer carrier board base support$3 handl$4 donor$3))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/29 12:16
S69	285	S67 and ((rebond$4 depond$4 detach$4 remov$4 separat$4) near3 (substrate wafer carrier board base support$3 handl$4 donor$3))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/29 12:19
S70	259	S69 and ((rebond$4 depond$4 detach$4 remov$4 separat$4) with (semiconduct$4 $4silicon acti$4) with (substrate wafer carrier board base support$3 handl$4 donor$3))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/29 17:02
S71	32	S68 not S70	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/29 17:47
S72	50	S67 not S70	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/29 12:40
S73	4	"6956268"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/29 12:30
S74	21726	(((depond$4 detach$4 split$4 remov$4 separat$4) with (substrate wafer carrier board base support$3 handl$4 donor$3)) and ((week$4 weak$4 low$3 less$3) with (bond$4 glue$4 stick$4 past$4 attach$4 adhes$4 coupl$3))).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/30 11:14
S75	3822	S74 and ((strong or streng$5 or great$3 high$3) with (bond$4 glue$4 stick$4 past$4 attach$4 adhes$4 coupl$3)).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/29 17:48

S76	53	S75 and (("SOI" or ((buried embed$3) with ($2oxide dielectric insulat$3))) with (substrate wafer carrier board base support$3 handl$4 donor$3)).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/29 17:10
S77	10221	((depond$4 detach$4 split$4 remov$4 separat$4 peel$4) with (substrate wafer carrier board base support$3 handl$4 donor$3)) and ((weak$4 low$3 less$3) with (bond$4 glue$4 stick$4 past$4 attach$4 adhes$4 coupl$3)) and ("SOI" (silicon adj2 insulat$4) ((buried embed$3) near2 ($2oxide dielectric insulat$3)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/29 17:59

| S78 | 259 | (US-20060189096-$ or US-20050258489-$ or US-20050042840-$ or US-20050029594-$ or US-20050029592-$ or US-20040253458-$ or US-20040171233-$ or US-20040169225-$ or US-20040157402-$ or US-20040102021-$ or US-20040082146-$ or US-20040067621-$ or US-20040063322-$ or US-20040048446-$ or US-20030203547-$ or US-20030190794-$ or US-20030087503-$ or US-20030045019-$ or US-20030020096-$ or US-20030017679-$ or US-20030008477-$ or US-20020185684-$ or US-20020132451-$ or US-20020127820-$ or US-20020121655-$ or US-20020102816-$).did. or (US-20020094668-$ or US-20020093047-$ or US-20020089016-$ or US-20020070291-$ or US-20020068419-$ or US-20020045327-$ or US-20020024152-$ or US-20020016020-$ or US-20020004286-$ or US-20010055863-$ or US-20010046746-$ or US-20010041423-$ or US-20010029060-$ or US-20010019153-$ or US-20010016401-$ or US-20010007367-$ or US-20010003668-$).did. or (US-7067396-$ or US-7045439-$ or US-7014748-$ or US-6993826-$ or US-6979629-$ or US-6936482-$ or US-6900114-$ or US-6895136-$ or US-6890835-$ or US-6881644-$ or US-6860963-$ or US-6848306-$ or US-6846723-$ or US-6846718-$ or US-6844243-$ or US-6838301-$ or US-6809009-$ or US-6774435-$ or US-6774010-$ or US-6773951-$ or US-6773534-$ or US-6759282-$ or US-6746559-$ or US-6709966-$ or US-6680260-$ or US-6672358-$).did. or (US-6670212-$ or US-6656271-$ or US-6653206-$ or US-6653205-$ or US-6639327-$ or US-6638834-$ or US-6635552-$ or US-6630713-$ or US-6624047-$ or US-6624046-$ or US-6617657-$ or US-6609553-$ or US-6605518-$ or US-6600231-$ or US-6597039-$ or US-6596610-$ or US-6593211-$ or US-6569748-$ or US-6566233-$ or US-6544837-$ or US-6540861-$ or US-6538330-$ or US-6537846-$ or US-6534384-$ or US-6534383-$ or US-6534382-$ or US-6534381-$).did. or (US-6534380-$ or US-6527031-$ or US-6524935-$ or US-6521078-$ or US-6513564-$ or US-6498073-$ or US-6492682-$ or US-6486008-$ or US-6482725-$ or US-6475323-$ or US-6475072-$ or US-6472711-$ or US-6472244-$ or US-6468923-$ or US-6468663-$ or US-6461939-$ or US-6455398-$ or US-6436226-$ or US-6429095-$ or US-6428620-$ or US-6427748-$ or US-6426270-$ or US-6423613-$ or US-6423563-$ or US-6418999-$ or US-6417108-$ or US-6410436-$).did. or (US-6399516-$ or US-6382292-$ or US-6362077-$ or US-6352909-$ or US-6346735-$ or US-6346435-$ or US-6342433-$ or US-6331473-$ or US-6329265-$ or US-6328796-$ or US-6326285-$ or US-6326279-$ or US-6323108-$ or US-6313012-$ or US-6312797-$ or US-6309950-$ or US-6309945-$ or US-6306730-$ or US-6306729-$ or US-6303977-$ or US-6291315-$ or US-6287885-$ or US-6284629-$ or US-6284628-$ or US-6281551-$ or US-6281033-$ or US-6265238-$).did. or (US-6263941-$ or US-6255731-$ or US-6248610-$ or US-6246068-$ or US-6245645-$ or US-6242324-$ or US-6239004-$ or US-6225192-$ or US-6224668-$ or US-6221738-$ or US-6211041-$ or US-6200878-$ or US-6194290-$ or US-6191007-$ or US-6171932-$ or US-6156624-$ or US-6153495-$ or US-6150239-$ or US-6143629-$ or US-6143628-$ or US-6140210-$ or US-6140209-$ or US-6121117-$ or US-6110391-$ or US-6100570-$ or US-6100166-$ or US-6100165-$).did. or (US-6093623-$ or US-6093577-$ or US-6063686-$ or US-6057212-$ or US-6054371-$ or US-6051855-$ or US-6020215-$ or US-6008110-$ or US-6004865-$ or US-5998281-$ or US-5994750-$ or US-5980633-$ or US-5976953-$ or US-5966620-$ or US-5963785-$ or US-5937312-$ or US-5923637-$ or US-5918139-$ or US-5880010-$ or US-5877070-$ or US-5876497-$ or US-5869387-$ or US-5869386-$ or US-5854123-$ or US-5849627-$ or US-5843832-$ or US-5840616-$).did. or (US-5834812-$ or US-5773355-$ or US-5769991-$ or US-5768903-$ or US-5750000-$ or US-5728824-$ or US-5721162-$ or US-5710057-$ or US-5705421-$ or | US-PGPUB; USPAT | OR | ON | 2006/08/29 17:47 |

S79	50	(US-20060125058-$ or US-20050059218-$ or US-20050026339-$ or US-20050009288-$ or US-20040253794-$ or US-20040229443-$ or US-20040081805-$ or US-20030155568-$ or US-20030148549-$ or US-20020119640-$).did. or (US-7081657-$ or US-7029993-$ or US-6716722-$ or US-6554046-$ or US-6538296-$ or US-6497763-$ or US-6388290-$ or US-6335535-$ or US-6242817-$ or US-6225190-$ or US-6221740-$ or US-6198159-$ or US-6171931-$ or US-6091112-$ or US-6060336-$ or US-6013935-$ or US-5985681-$ or US-5969401-$ or US-5915193-$ or US-5882532-$ or US-5855693-$ or US-5804494-$ or US-5650042-$ or US-5569620-$ or US-5556503-$ or US-5413955-$).did. or (US-5407856-$ or US-5387555-$ or US-5266824-$ or US-5264395-$ or US-5258318-$ or US-5227339-$ or US-5084419-$ or US-5071785-$ or US-5034343-$ or US-5032544-$ or US-4962879-$ or US-4883215-$ or US-4826787-$ or US-4638552-$).did.	US-PGPUB; USPAT	OR	ON	2006/08/29 17:47
S80	32	(US-20050059218-$ or US-20050009288-$ or US-20040253794-$ or US-20040229443-$ or US-20040081805-$ or US-20030155568-$).did. or (US-7081657-$ or US-7029993-$ or US-6716722-$ or US-6554046-$ or US-6497763-$ or US-6388290-$ or US-6335535-$ or US-6225190-$ or US-6221740-$ or US-6198159-$ or US-6013935-$ or US-5882532-$ or US-5804494-$ or US-5569620-$ or US-5413955-$ or US-5407856-$ or US-5387555-$ or US-5266824-$ or US-5258318-$ or US-5227339-$ or US-5071785-$ or US-5034343-$ or US-5032544-$ or US-4962879-$ or US-4883215-$ or US-4826787-$).did.	US-PGPUB; USPAT	OR	ON	2006/08/29 17:47
S81	6278	S77 and ((strong or streng$5 or great$3 high$3) with (bond$4 glue$4 stick$4 past$4 attach$4 adhes$4 coupl$3))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/29 17:49
S82	5930	S81 not (S76 S78 S79 S80)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/29 17:49
S83	3153	S82 and (@ad<"20010912" @rlad<"20010912")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/29 17:49
S85	2525	S83 and ((depond$4 detach$4 split$4 remov$4 separat$4 peel$4) with (semiconduct$4 $4silicon device "IC" die chip))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/29 17:55
S87	1725	S85 and ((depond$4 detach$4 split$4 remov$4 separat$4) with (semiconduct$4 $4silicon) with (substrate wafer carrier board base support$3 handl$4 donor$3))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/29 17:58
S88	510	S87 and ((weak$4 low$3 less$3) with (bond$4 glue$4 stick$4 past$4 attach$4 adhes$4 coupl$3) with (chip die "IC" device))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/29 18:01

EAST Search History

S89	374	S88 and ((die chip "IC" device) with (bond$4 glue$4 stick$4 past$4 attach$4 adhes$4 coupl$3) with (substrate wafer board base "PCB" "PWB" carrier))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/29 18:03
S90	63	("4309225" | "4370176" | "4371421" | "4471003" | "4479846" | "4500563" | "4585945" | "4816420" | "4837182" | "4846931" | "4883561" | "5273616" | "5362682" | "5374564" | "5453153" | "5559043" | "5588994" | "5676752" | "5710057" | "5714395" | "5793115" | "5845123" | "5877070" | "5882987" | "5897939" | "5909627" | "5920764" | "5933750" | "5976953" | "5985688" | "5993677" | "5994207" | "6020252" | "6027988" | "6033974" | "6054363" | "6054370" | "6059877" | "6071795" | "6103597" | "6137110" | "6146979" | "6155909" | "6159323" | "6159824" | "6159825" | "6162705" | "6184060" | "6184111" | "6187110" | "6190937" | "6190998" | "6191007" | "6204151" | "6214733" | "6221738" | "6221740" | "6221774" | "6225190" | "6225192" | "6232136" | "6309945" | "6387736").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/29 18:33
S91	136	S88 not S89	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/29 18:46
S92	16	"6342433"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/30 11:13
S93	13	S92 and ((depond$4 detach$4 split$4 remov$4 separat$4) with (substrate wafer carrier board base support$3 handl$4 donor$3)) and (bond$4 glue$4 stick$4 past$4 attach$4 adhes$4 coupl$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/30 11:19